



GN012 Application Note

Gate Driver Circuit Design with GaN E-HEMTs

March 08, 2022

GaN Systems Inc.

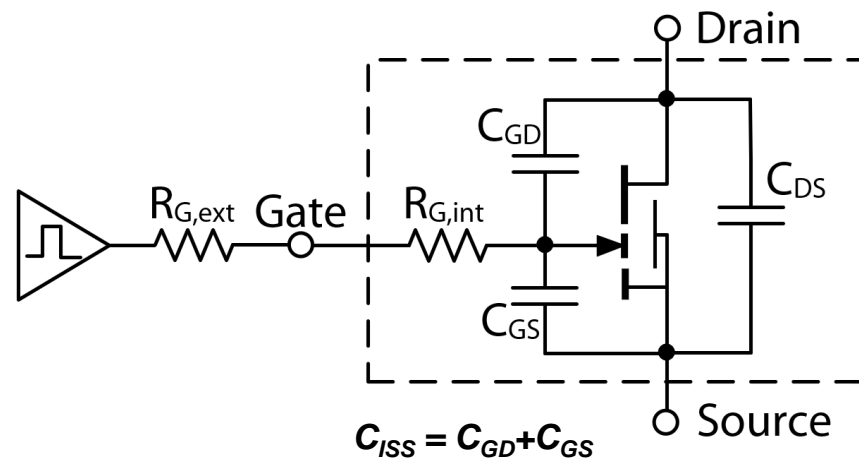


Common with Si MOSFET

- True enhancement-mode normally off
- Voltage driven - driver charges/discharges C_{ISS}
- Supply Gate leakage I_{GSS} only
- Easy slew rate control by R_G
- Compatible with Si gate driver chip

Differences

- Much Lower Q_G : Lower drive loss; faster switching
- Higher gain and lower V_{GS} : +5-6V gate bias to turn on
- Lower $V_{G(th)}$: typ. 1.5V



Versus other enhancement-mode GaN








- More robust gate: -20/+10V max rating
- **No DC gate drive current required**
- **No complicated gate diode / PN junction**

Gate Bias Level	GaN Systems GaN E-HEMT	Si MOSFET	IGBT	SIC MOSFET
Maximum rating	-20/+10V	-/+20V	-/+20V	-8/+20V
Typical gate bias values	0 or -3/+5-6V	0/+10-12V	0 or -9/+15V	-4/+15-20V

❖ GaN HEMTs are **simple to drive**





- GaN Systems GaN HEMTs are compatible with most drivers for silicon devices.
- When the driver supply voltage (V_{DD}) is higher than +6V (the recommended turn-on V_{GS} for GaN), a negative V_{GS} generating circuit is required to convert the V_{GS} into +6/-(V_{DD} -6) V, refer to page 7.
- V_{DD} is recommended to $\leq 12V$.

Most popular solutions:

Gate Drivers	Configuration	Isolation	Notes
 Si8271	Single switch	Isolated	Split outputs
 Si8273/4/5	Half-Bridge	Isolated	Dead time programmability
 ADuM4121ARIZ	Single Switch	Isolated	Internal miller clamp
 ACPL-P346	Single Switch	Isolated	Internal miller clamp
 HEY1011	Single Switch	Isolated	Power Rail Integrated
 NCP51820	Half Bridge	Non-Isolated	Bootstrap voltage management
 RAA226110	Single Switch	Non-Isolated	Programmable Source Current and Adjustable Overcurrent Protection





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Most popular solutions:

Gate Drivers	Configuration	Split Outputs	Bootstrap voltage management	Notes
 NCP51810	Half-Bridge	Yes	Yes	High Speed
 uP1966A	Half-Bridge	Yes	Yes	General Purpose
 LMG1205	Half-Bridge	Yes	Yes	General Purpose
 MDC901	Half-Bridge	Yes	Yes	High Current






- GaN Systems GaN HEMTs are compatible with most of the controllers for silicon devices.
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Most popular solutions:

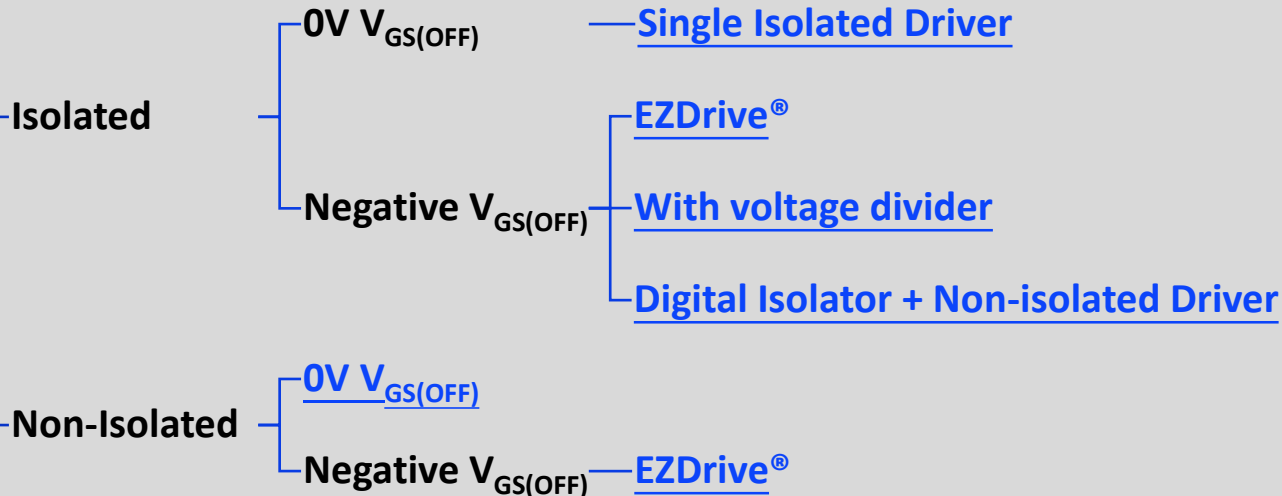
Configurations	Controllers	Description
Flyback - Adapters - Chargers - Other low-power AC/DCs	 NCP1342	650V, Quasi-resonant
	 UCC28600	600V, Quasi-resonant
	 NCP1250	650V, Fixed frequency
Sync Buck DC/DC (48V/12V)	 LTC7800	60V, Sync rectifier control, up to 2.2MHz

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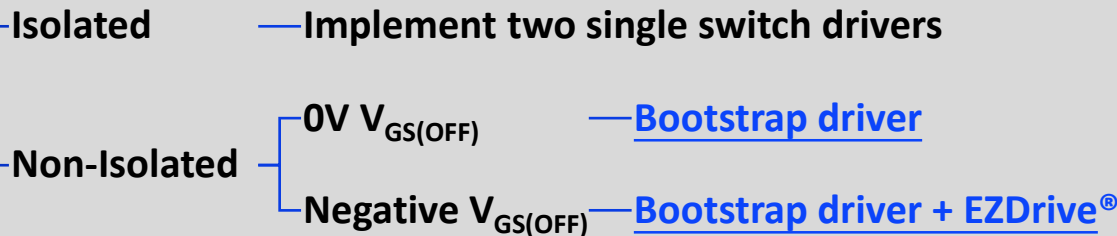
Most popular solutions:

Configurations	Controllers	Notes
LLC - Adapters - Chargers - Flat panel displays - Industrial power	 ON Semiconductor	NCP13992 600V, current mode controller
		NCP1399 600V, current mode controller, off-mode operation
	 TEXAS INSTRUMENTS	UCC256404 600V, optimized burst mode, low audible noise and standby power
		UCC256301 600V, hybrid hysteric mode, low standby power, wide operating frequency
PFC - PC Power Supplies - Appliances - LED Drivers	 ON Semiconductor	NCP1615 / NCP1616 700V, critical conduction mode operation
	 TEXAS INSTRUMENTS	UCC28180 Programable frequency, continuous conduction mode operation, no AC line HV sensing
PFC + LLC	 MPS Monolithic Power Systems, Inc.	HR1203 700V, CCM/DCM Multi-mode PFC control, adjustable dead-time and bust mode switching LLC

Single switch driver



Half/Full Bridge driver

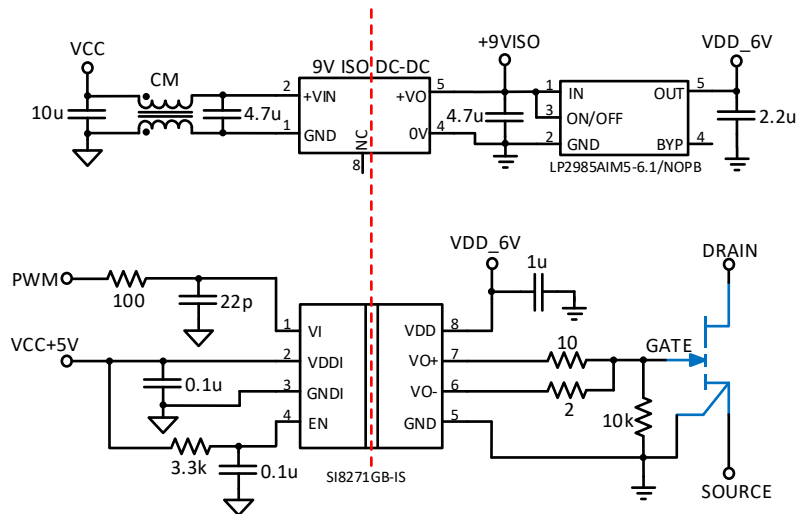


Paralleling GaN

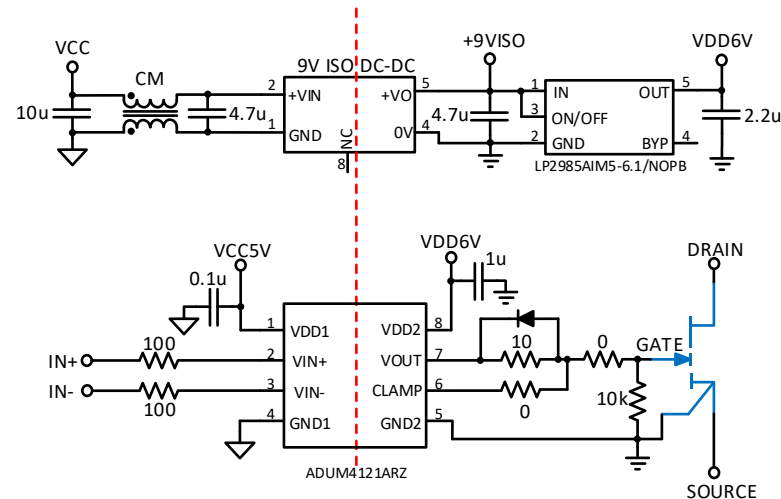
— Driver Circuit for GaN HEMT in Parallel

* When is negative $V_{GS(OFF)}$ needed?

- 0V $V_{GS(OFF)}$ for low voltage or low power applications, or where the deadtime loss is critical
- Optional CM Choke for better noise immunity

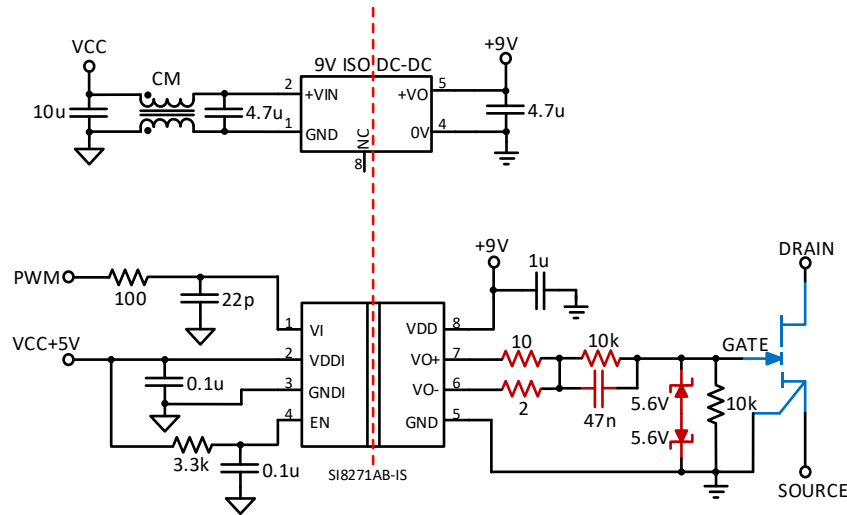


Example I: Driver with separate outputs for switch ON/OFF (SI8271)



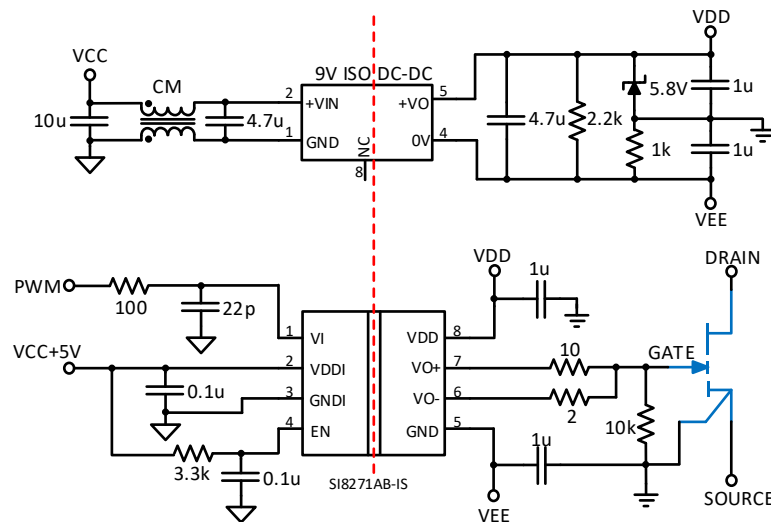
Example II: Driver with single output for switch ON and OFF (ADUM4121)

- Negative V_{GS} voltage is applied by the 47nF capacitor
- Compatible with bootstrap circuit
- Applicable from 1kW ~ 100kW power range
- Optional CM Choke for better noise immunity



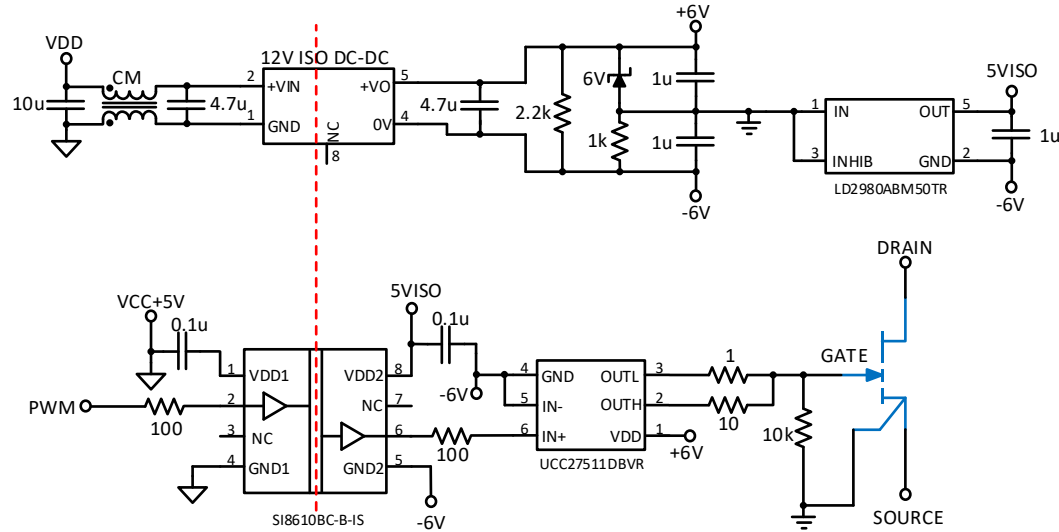
Example: SI8271 EZDrive® circuit ($V_{GS}=+6V/-3V$)

- Negative V_{GS} voltage is generated by the voltage divider (5.8V Zener diode and 1kOhm resistor)
- Robust and easy to layout
- Applicable for applications from low power to higher power (1kW ~ 100kW)
- Optional CM Choke for better noise immunity



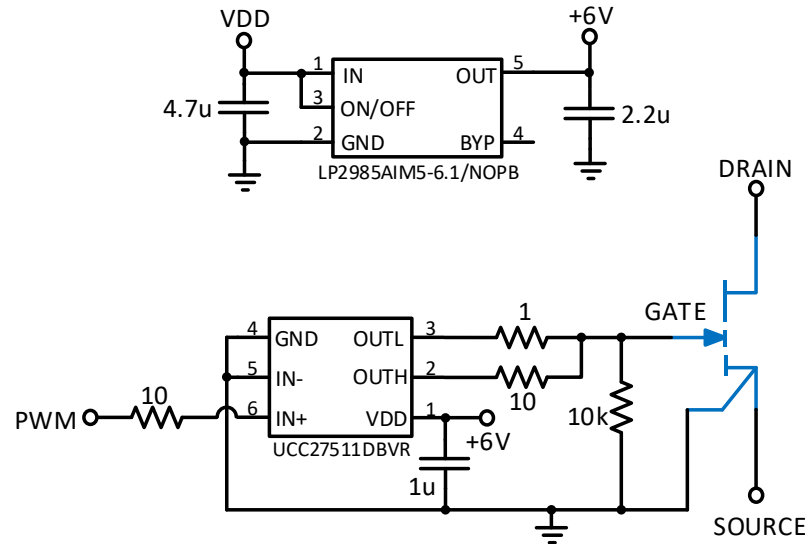
Example: SI8271 driving circuit with voltage divider ($V_{GS}=+6V/-3V$)

- To enable non-isolated driver or buffer with high sink current capability where isolation is required
- For high power applications: e.g. EV motor drive, PV inverter, etc
- Optional CM Choke for better noise immunity



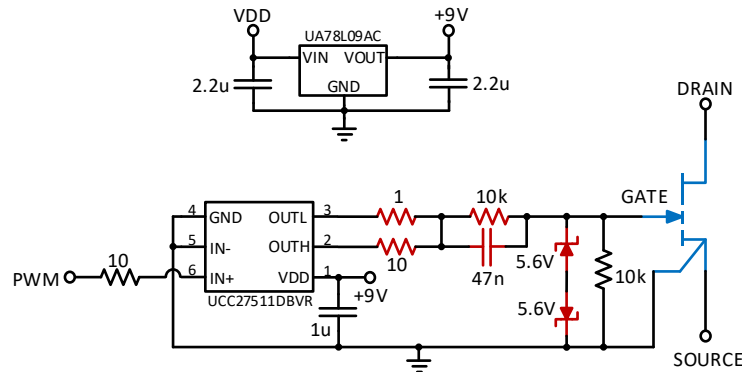
Example: SI8610 (digital isolator) + UCC27511 (Non-isolated driver) ($V_{GS} = +6V/-6V$)

- For single-ended applications (Class E, Flyback, Push-pull etc)
- Or to work with a digital isolator for the high-side switch



Example: UCC27511 driving circuit ($V_{GS}=+6V/0V$)

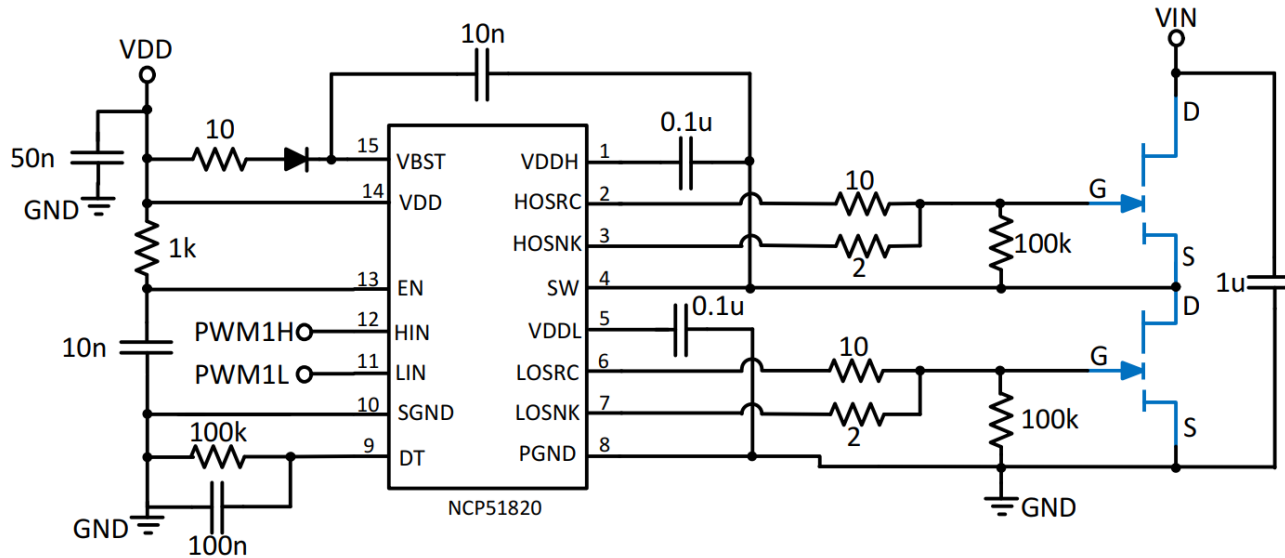
- Negative V_{GS} voltage is applied by the 47nF capacitor
- Compatible with bootstrap circuit
- Optional CM Choke for better noise immunity



Example: UCC27511 driving circuit ($V_{GS}=+6V/-3V$)

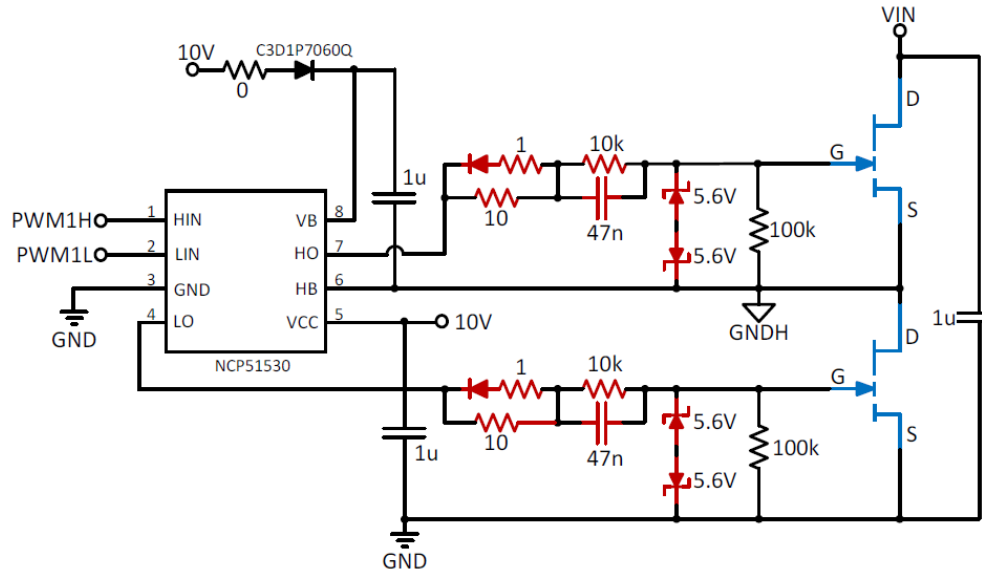
For more info about GaN EZDrive®, please refer to GN010: <https://gansystems.com/>

- For low power applications
- Choose the bootstrap diode with low C_J and fast recovery time



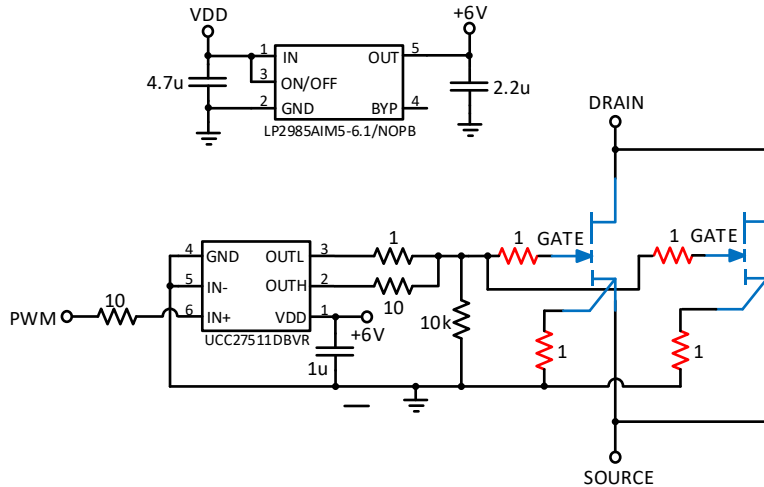
Example: NCP51820 Bootstrap driving circuit ($V_{GS}=+6V/0V$)

- EZDrive® can get a negative voltage on 47nF capacitor, which can be used as turn off voltage
- Turn on/off slew rate is controllable with external resistors to optimize EMI
- Suitable for low power application

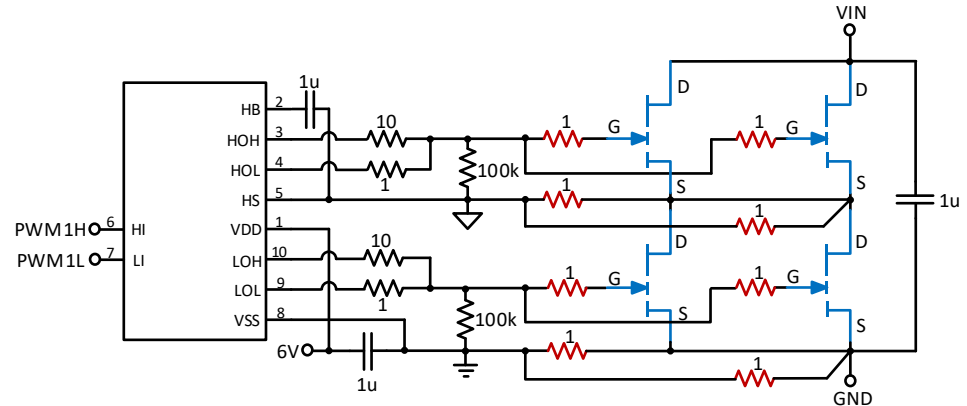


Example: NCP51530 Bootstrap driving circuit with EZdrive® ($V_{GS}=+6V/-3V$)

- For HEMTs in parallel, add additional 1ohm gate and source resistors (as **highlighted** below)



Example: UCC27511 non-isolated driving circuit for single GaN ($V_{GS}=+6V/0V$)



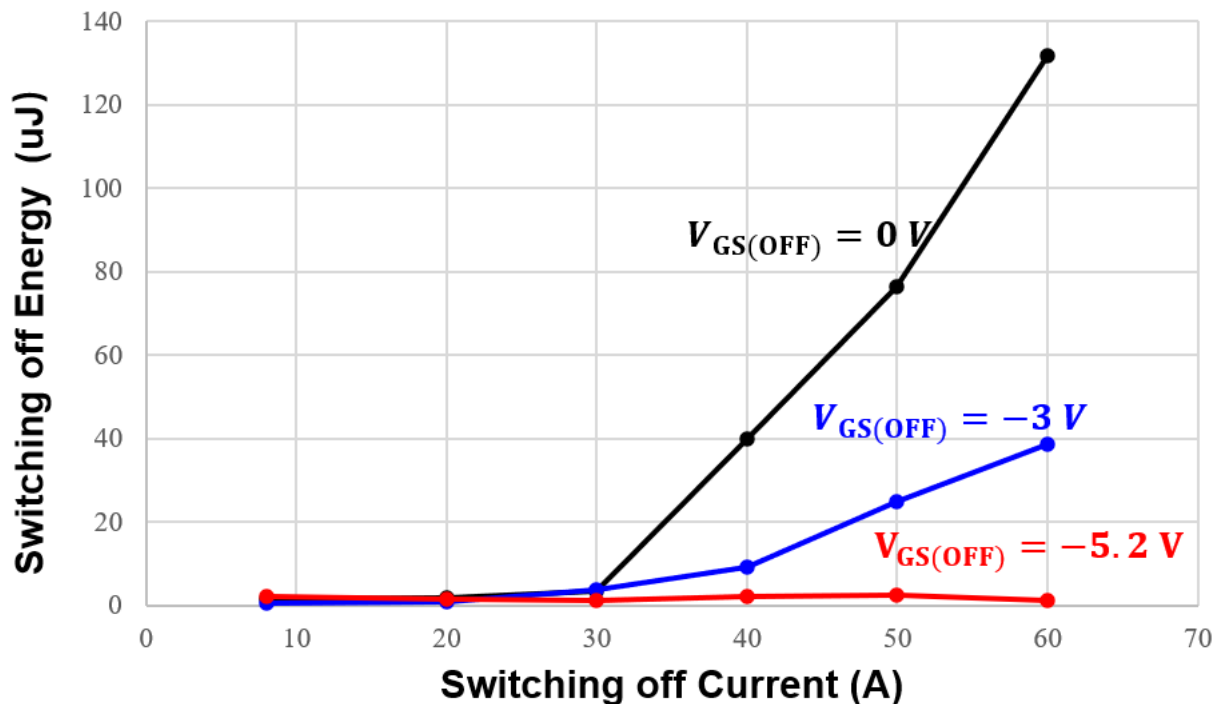
Example: Bootstrap driving circuit for half-bridge ($V_{GS}=+6V/0V$)

- Gate driving tips for $V_{GS(OFF)}$
- When is $V_{GS(OFF)}$ needed?
- $V_{GS(OFF)}$ vs. Switching-off Loss
- Trade-off between Switching-off Loss and Deadtime Loss

When is negative $V_{GS(OFF)}$ needed?

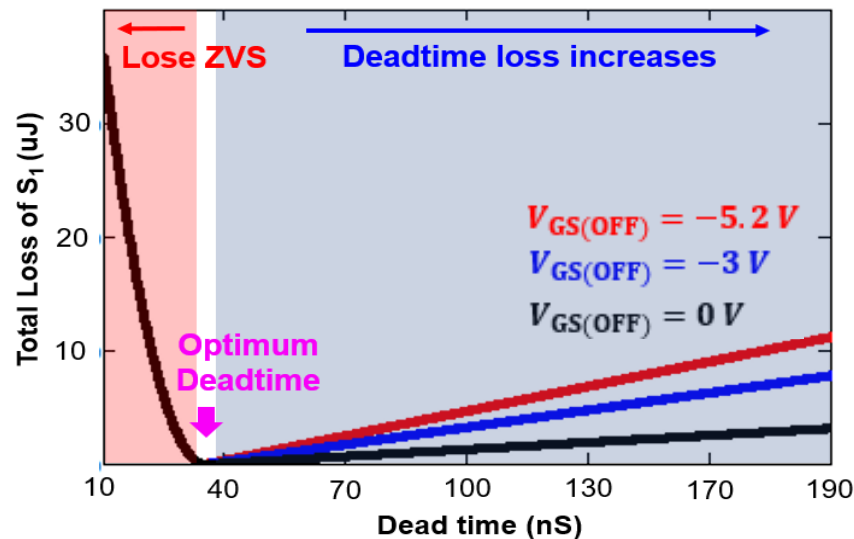
- Negative $V_{GS(OFF)}$ can increase noise immunity
- Negative $V_{GS(OFF)}$ can reduce switching-off loss especially under high-current
- Deadtime loss increases as Negative $V_{GS(OFF)}$ increase (more info please refer to page 8, APPNOTE GN001)
- There is a tradeoff between switching-off and deadtime loss for $V_{GS(OFF)}$ selection. -3V $V_{GS(OFF)}$ is recommended to start with for above 0.5kW applications.

$V_{GS(OFF)}$ vs. Switching-off Loss

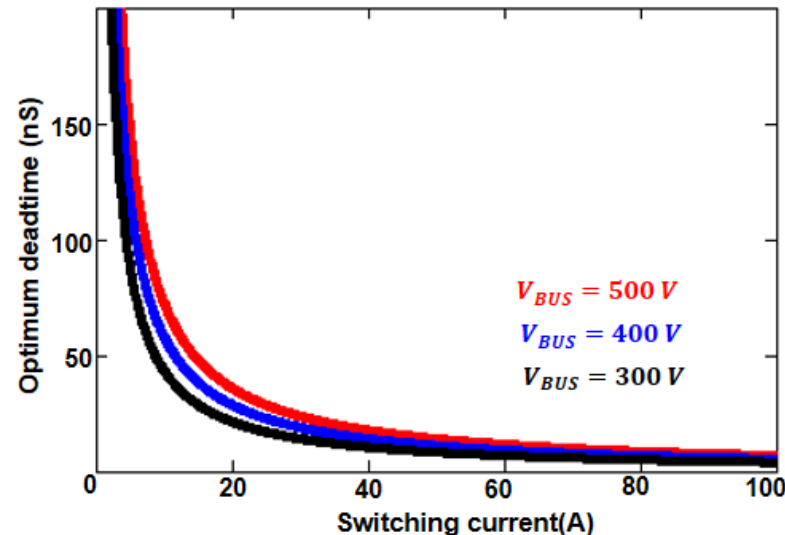


Switching-off loss of GS66516B vs. current at $V_{BUS}=400\text{ V}$, 25°C , $R_G=1\Omega$

Negative V_{DROff} **reduces the switching off energy** under high current.



Relation between total loss and deadtime of GS66516B at $I_D=10A$, 25 °C



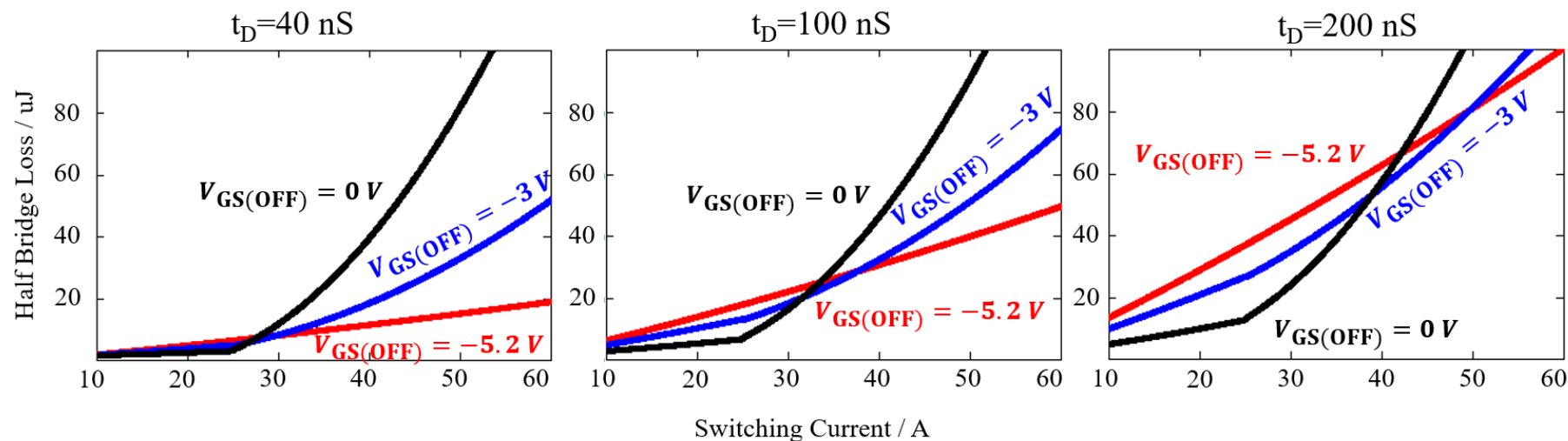
Optimum deadtime Vs. switching off current at $V_{BUS}=400V$

ZVS boundary:

$$t_d > \frac{C_{eq} \cdot V_{bus}}{i_{switching}} \quad (1)$$

$$0.5 \cdot L \cdot i_{Smin}^2 > i_{Smin} \cdot V_{SD} \cdot \left(t_d - \frac{C_{eq} \cdot V_{DC}}{i_{Smin}} \right) + 0.5 \cdot C_{eq} \cdot V_{DC}^2 \quad (2)$$

- Deadtime loss increases as $V_{GS(OFF)}$ increases
- A too short dead time will result in losing ZVS, while a too long dead time will cause additional loss



Half-bridge overall loss vs. switching current under different negative turn-off gate voltage V_{DROff}
 (a) with deadtime $t_D = 40$ nS, (b) with deadtime $t_D = 100$ nS, (c) with deadtime $t_D = 200$ nS.

- **Negative V_{DROff}** will make the power stage more efficient under **higher power**.
- **Precise dead time control** is the key to higher system efficiency.



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